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1000W, 50V Avionics RF LDMOS FETs

Description

The MQ121K0VP is a 1000W, high performance, internally matched LDMOS FET, designed for avionics applications with frequencies 960-1215MHz

It is featured for high power and high ruggedness.

It is recommended to use this device under pulse condition only

Typical Pulse Performance (on innogration wide band test fixture with device soldered):
Vds = 50 V, Idq = 100 mA, TA = 25 °C, Pulse condition: 1%, 10us

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Freq	P1dB	P1dB	P1dB	P1dB	P3dB	P3dB	P3dB
(MHz)	(dBm)	(W)	Eff(%)	Gain(dB)	(dBm)	(W)	Eff(%)
960	60.66	1164.0	49.5	12.95	61.39	1377.1	51.3
1030	59.85	965.8	49.9	13.87	60.72	1180.8	51.6
1090	59.9	976.3	51.9	14.08	60.62	1154.0	52.6
1130	59.76	945.4	49.4	13.45	60.49	1119.9	50.0
1160	59.76	946.8	48.5	11.53	60.48	1116.5	49.2
1180	59.96	990.8	49.5	12.57	60.55	1135.6	50.1
1200	60.19	1043.9	50.3	12.24	60.77	1194.2	50.2
1215	59.87	970.9	49.7	12.16	60.57	1139.8	50.1

Features

- High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- Internally Matched for Ease of Use
- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- Excellent thermal stability, low HCI drift
- Compliant to Restriction of Hazardous Substances (RoHS) Directive 2002/95/EC

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
DrainSource Voltage	V _{DSS}	115	Vdc
GateSource Voltage	V _{GS}	-10 to +10	Vdc
Operating Voltage	V_{DD}	+55	Vdc
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	Tc	+150	°C
Operating Junction Temperature	T₃	+225	°C

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case, Case Temperature			
80°C, 870W Pout, Pulse width: 100us, duty cycle: 10%,	RеJC	0.02	°C/W
Vds=50 V, IDQ = 100 mA			

Table 3. ESD Protection Characteristics

Test Methodology	Class
Human Body Model (per JESD22A114)	Class 2



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Table 4. Electrical Characteristics (TA = 25 °C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit	
OC Characteristics						
Drain-Source Breakdown Voltage		115				
$(V_{GS}=0V; I_{D}=100uA)$	V _{DSS}	115			V	
Zero Gate Voltage Drain Leakage Current				10		
$(V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V})$	I _{DSS}			10	μА	
GateSource Leakage Current				1	^	
$(V_{GS} = 6 \text{ V}, V_{DS} = 0 \text{ V})$	I _{GSS}			I	μΑ	
Gate Threshold Voltage	V (4)		1.6		V	
$(V_{DS} = 50V, I_D = 600 \text{ uA})$	V _{GS} (th)		1.0		V	
Gate Quiescent Voltage	V		3		V	
$(V_{DD} = 50 \text{ V}, I_{DQ} = 100 \text{ mA}, \text{ Measured in Functional Test)}$	$V_{GS(Q)}$		3		V	

Reference Circuit of Test Fixture

(Layout file upon request) PCB: Roger 4350B, 20mils

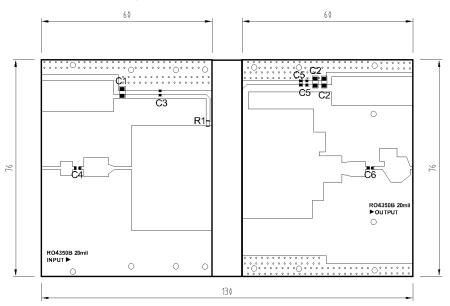
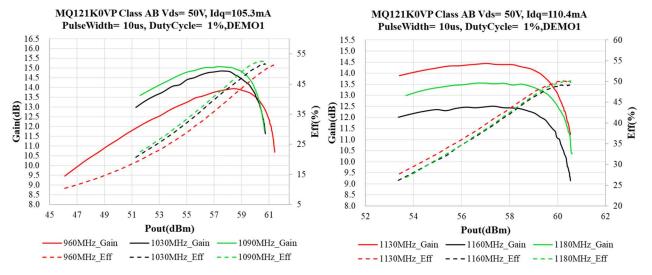


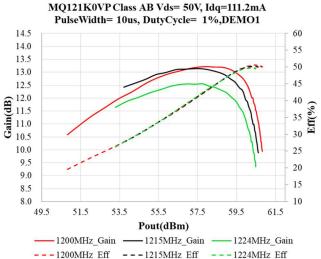
Figure 1. Test Circuit Component Layout

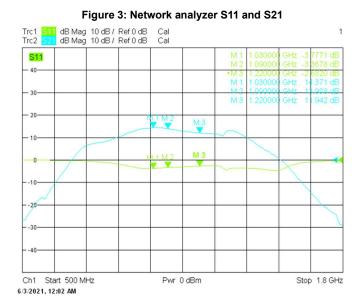
Component	Description	Suggested Manufacturer
C1,C2	Ceramic multilayer capacitor, 10uF, 100V	10uF/100V
C3,C5	47pF	ATC800B
C4	100pF	ATC800B
C6	51pF	ATC800R
R1	Chip Resistor,9.1Ω,1206	
PCB	20mil thickness, εr=3.5, Ro4	350B, 1 oz. copper

TYPICAL CHARACTERISTICS

Figure 2: Power gain and Efficiency as a Function of Pout Pulse width: 10uS, duty cycle: 1%, Vds = 50 V, Idq = 100 mA,

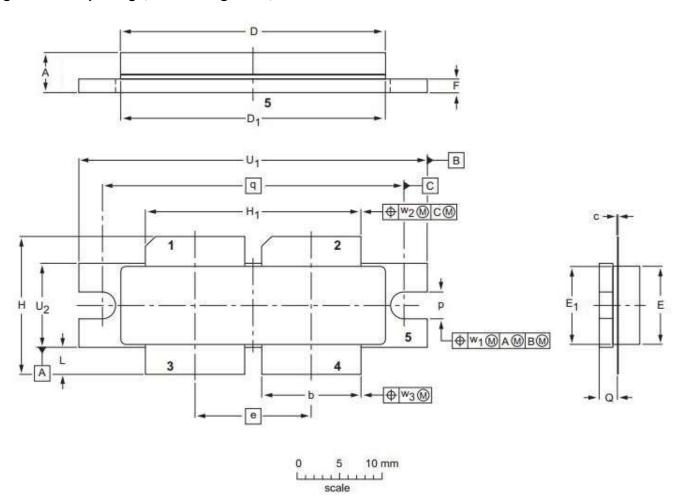






Package Outline

Flanged ceramic package; 2 mounting holes; 4 leads (1, 2—DRAIN, 3, 4—GATE, 5—SOURCE)



UNIT	Α	b	С	D	D ₁	е	E	E ₁	F	Н	H ₁	L	р	Q	q	U ₁	U ₂	W ₁	W_2	W ₂
Mm	4.7	11.81	0.18	31.55	31.52	13.72	9.50	9.53	1.75	17.12	25.53	3.48	3.30	2.26	35.56	41.28	10.29	0.25	0.51	0.25
IVIIII	4.2	11.56	0.10	30.94	30.96	13.72	9.30	9.27	1.50	16.10	25.27	2.97	3.05	2.01	33.30	41.02	10.03	0.25	0.51	0.25
Inches	0.185	0.465	0.007	1.242	1.241	0.540	0.374	0.375	0.069	0.674	1.005	0.137	0.130	0.089	1.400	1.625	0.405	0.01	0.02	0.01
inches	0.165	0.455	0.004	1.218	1.219	0.340	0.366	0.365	0.059	0.634	0.995	0.117	0.120	0.079	1.400	1.615	0.395	0.01	0.02	0.01

OUTLINE		REFERENCE	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA	PROJECTION	1000E DATE
PKG-D4E					03/12/2013

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Revision history

Table 6. Document revision history

Date	Revision	Datasheet Status
2021/6/3	Rev 1.0	Preliminary Datasheet Creation

Application data based on JF-21-04

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